



**THE DATASHEET OF
B39851B4404P810**





RF360
Europe GmbH

Data sheet

SAW duplexer
Automotive telematics
LTE band 20

Series/type:	B4404
Ordering code:	B39851B4404P810
Date:	October 17, 2019
Version:	2.2

DCN: 80-PA243-404 Rev. A

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1 Application

- Low-loss SAW duplexer for LTE Band 20 systems
- Very high isolation
- Usable pass band 30 MHz
- Single-ended to balanced transformation in Antenna-Rx path
- Impedance transformation 50 Ω to 100 Ω in Antenna-Rx path

2 Features

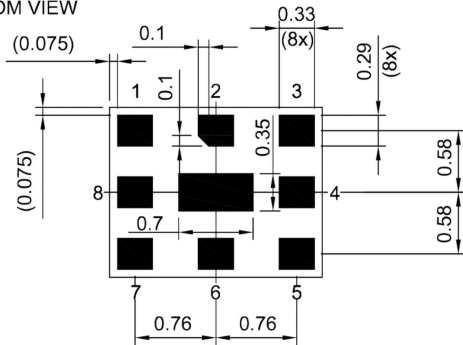
- Package size 2.0 \pm 0.1 mm \times 1.6 \pm 0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 5 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family (Grade 3: -40 $^{\circ}$ C to +85 $^{\circ}$ C)



Figure 1: Picture of component with example of product marking.

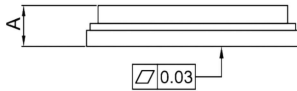
3 Package

BOTTOM VIEW

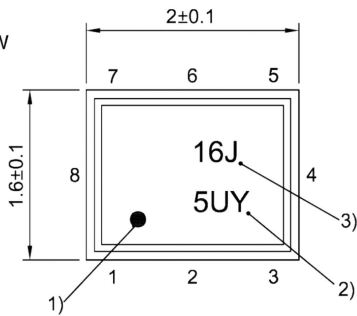


Pad and pitch tolerance ±0.05

SIDE VIEW

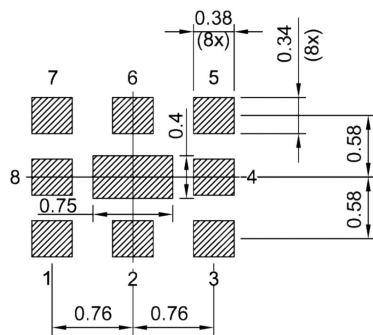


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern
THRU VIEW



Landing pad tolerance -0.02

4 Pin configuration

- 1, 8 RX balanced
- 3 TX
- 6 ANT
- 2, 4, 5, 7, 9 Ground

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 22).

5 Matching circuit

■ $L_{p1,8} = 43 \text{ nH}$

■ $L_{p6} = 9.0 \text{ nH}$

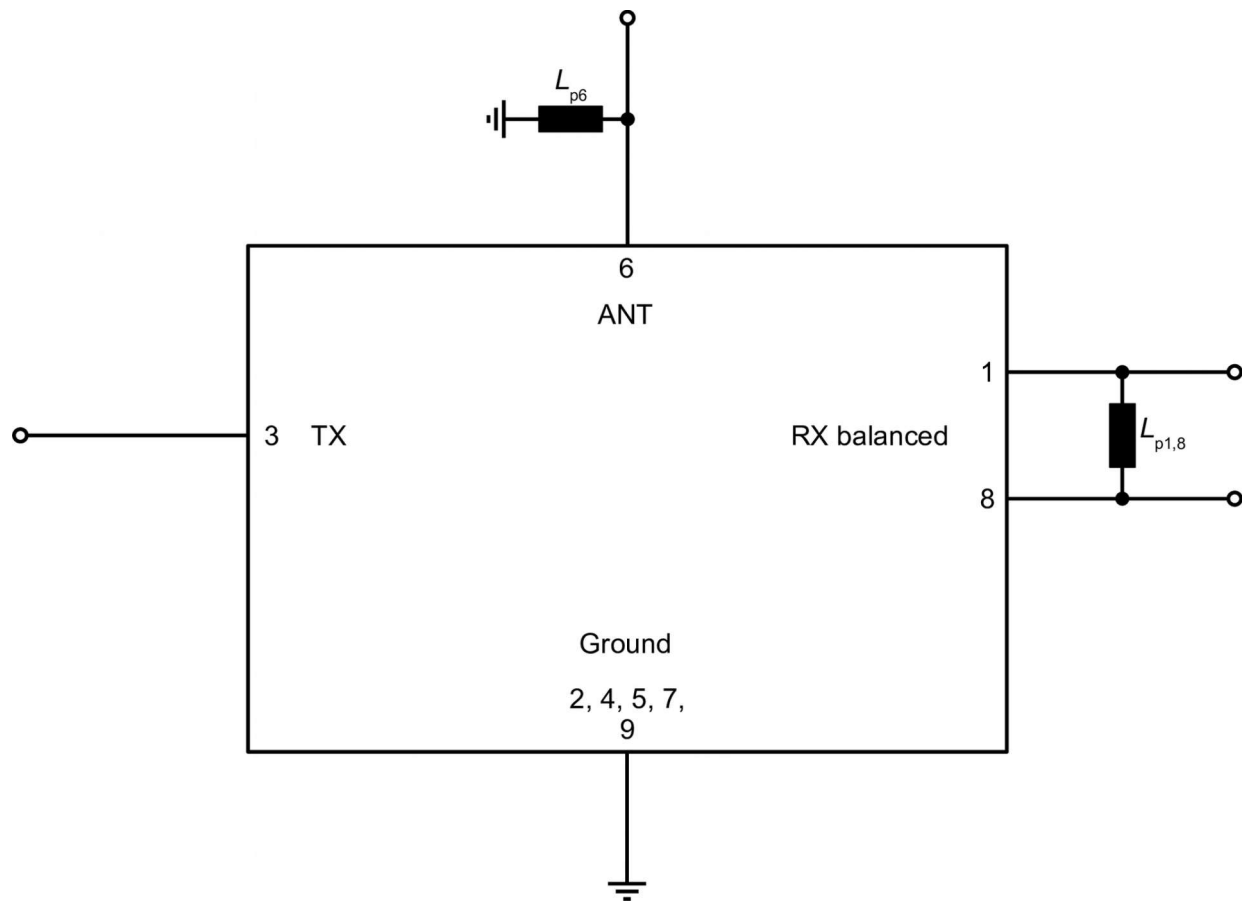


Figure 3: Schematic of matching circuit.

6 Characteristics

6.1 TX – ANT

Temperature range for specification	T_{SPEC}	= -15 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω // 9.0 nH ¹⁾
RX terminating impedance	Z_{RX}	= 100 Ω // 43 nH ¹⁾

Characteristics TX – ANT				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_c	—	847	—	MHz
Maximum insertion attenuation			α_{max}	—	2.2	3.6	dB
	832 ... 862	MHz		—	2.2	2.7 ²⁾	
Amplitude ripple (p-p)			$\Delta\alpha$	—	1.1	2.6	dB
	832 ... 862	MHz		—	1.1	2.6	
Maximum VSWR			$VSWR_{max}$	—	1.7	2.1	
@ TX port	832 ... 862	MHz		—	1.7	2.0	
@ ANT port	832 ... 862	MHz		—	1.7	2.0	
Minimum attenuation			α_{min}				
	100 ... 771	MHz		34	41	—	dB
	771 ... 791	MHz		35	46	—	dB
	791 ... 821	MHz		40	54	—	dB
	873 ... 903	MHz		13	32	—	dB
	925 ... 960	MHz		30	43	—	dB
	1565 ... 1606	MHz		40	50	—	dB
	1664 ... 2170	MHz		40	52	—	dB
	2400 ... 2620	MHz		35	39	—	dB
	2620 ... 2690	MHz		35	47	—	dB
	3328 ... 3448	MHz		20	43	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ In +25,+55 °C temperature range.

6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= -15 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω // 9.0 nH ¹⁾
RX terminating impedance	Z_{RX}	= 100 Ω // 43 nH ¹⁾

Characteristics ANT – RX				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_c	—	806	—	MHz
Maximum insertion attenuation			α_{max}				
	791... 821	MHz		—	2.6	3.9	dB
	791... 821	MHz		—	2.6	3.3 ²⁾	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	791... 821	MHz		—	1.3	2.8	dB
Maximum VSWR			VSWR _{max}				
@ ANT port	791... 821	MHz		—	1.8	2.2	
@ RX port	791... 821	MHz		—	2.2	2.5	
Minimum common-mode rejection ratio			CMRR _{min}				
	791... 821	MHz		23	28	—	dB
Minimum attenuation			α_{min}				
	100... 760	MHz		45	52	—	dB
	760... 782	MHz		25	50	—	dB
	832... 833.5	MHz		35	62	—	dB
	832... 862	MHz		50 ³⁾	53	—	dB
	833.5... 862	MHz		50	53	—	dB
	873... 903	MHz		40	55	—	dB
	1623... 1683	MHz		40	61	—	dB
	2400... 2545	MHz		40	55	—	dB
	2545... 4000	MHz		35	53	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ In +25,+55 °C temperature range.

³⁾ In +25,+85 °C temperature range.

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= -15 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω
ANT terminating impedance	Z_{ANT}	= 50 Ω // 9.0 nH ¹⁾
RX terminating impedance	Z_{RX}	= 100 Ω // 43 nH ¹⁾

Characteristics TX – RX			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Minimum isolation	α_{min}	791... 820.5 MHz	51	56	—	dB
		820.5... 821 MHz	45	60	—	dB
		832... 834 MHz	43	63	—	dB
		832... 834 MHz	52 ²⁾	63	—	dB
		834... 862 MHz	52	56	—	dB
		1574... 1577 MHz	40	69	—	dB
		1664... 1724 MHz	20	68	—	dB
		2496... 2586 MHz	20	63	—	dB
Minimum common-mode isolation	α_{min}	832... 862 MHz	60	64	—	dB

¹⁾ See Sec. Matching circuit (p. 6).

²⁾ In +25,+85 °C temperature range.

7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +85\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +85\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V (max.)}$	
Input power	P_{IN}	
@ TX port: 832 ... 862 MHz	28 dBm	Continuous wave for 5000 h @ 50 °C.
Elsewhere @ TX port	10 dBm	Continuous wave for 5000 h @ 50 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ In case of applied DC voltage blocking capacitors are mandatory.

8 Transmission coefficients

8.1 TX – ANT

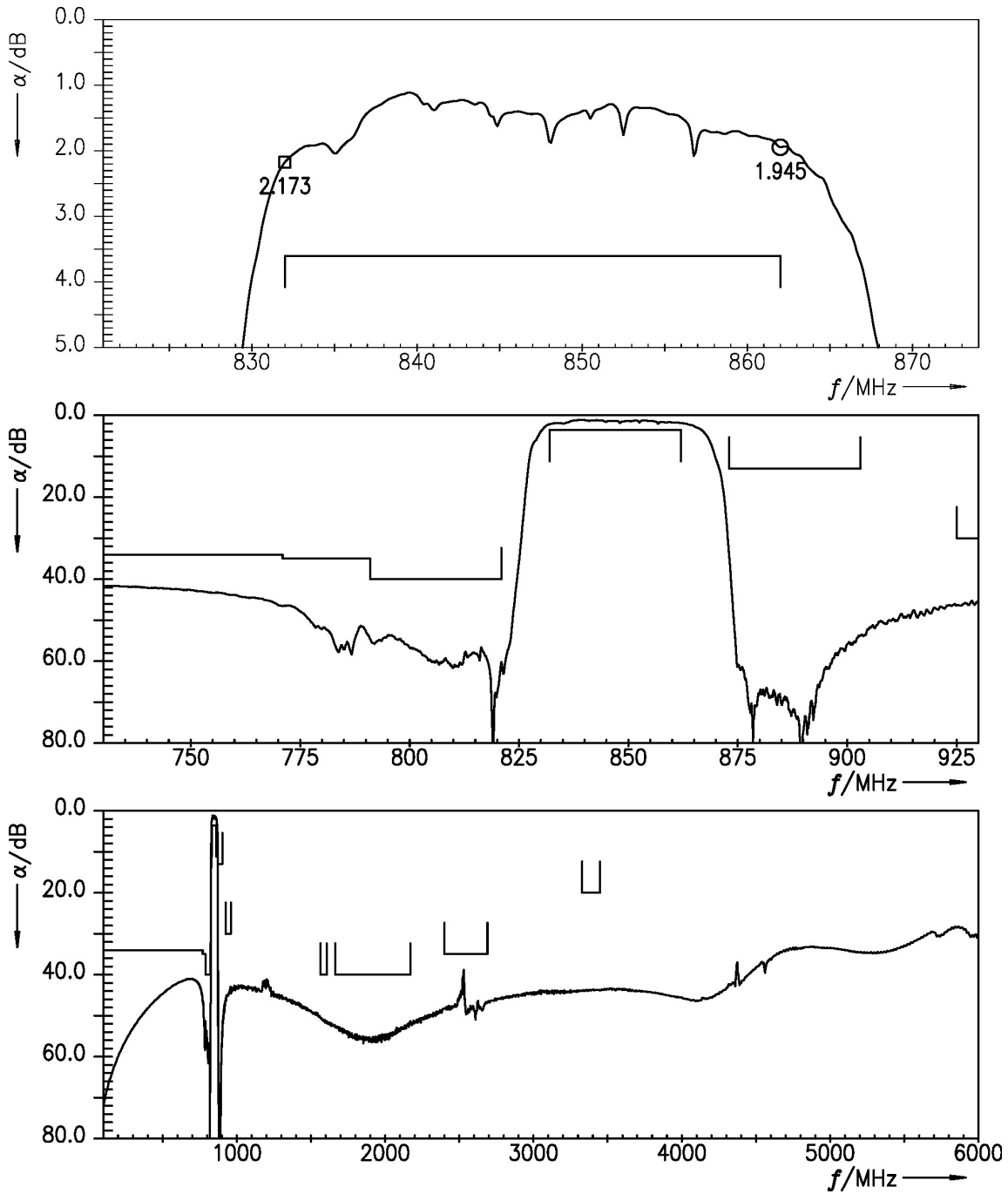


Figure 4: Attenuation TX – ANT.

8.2 ANT – RX

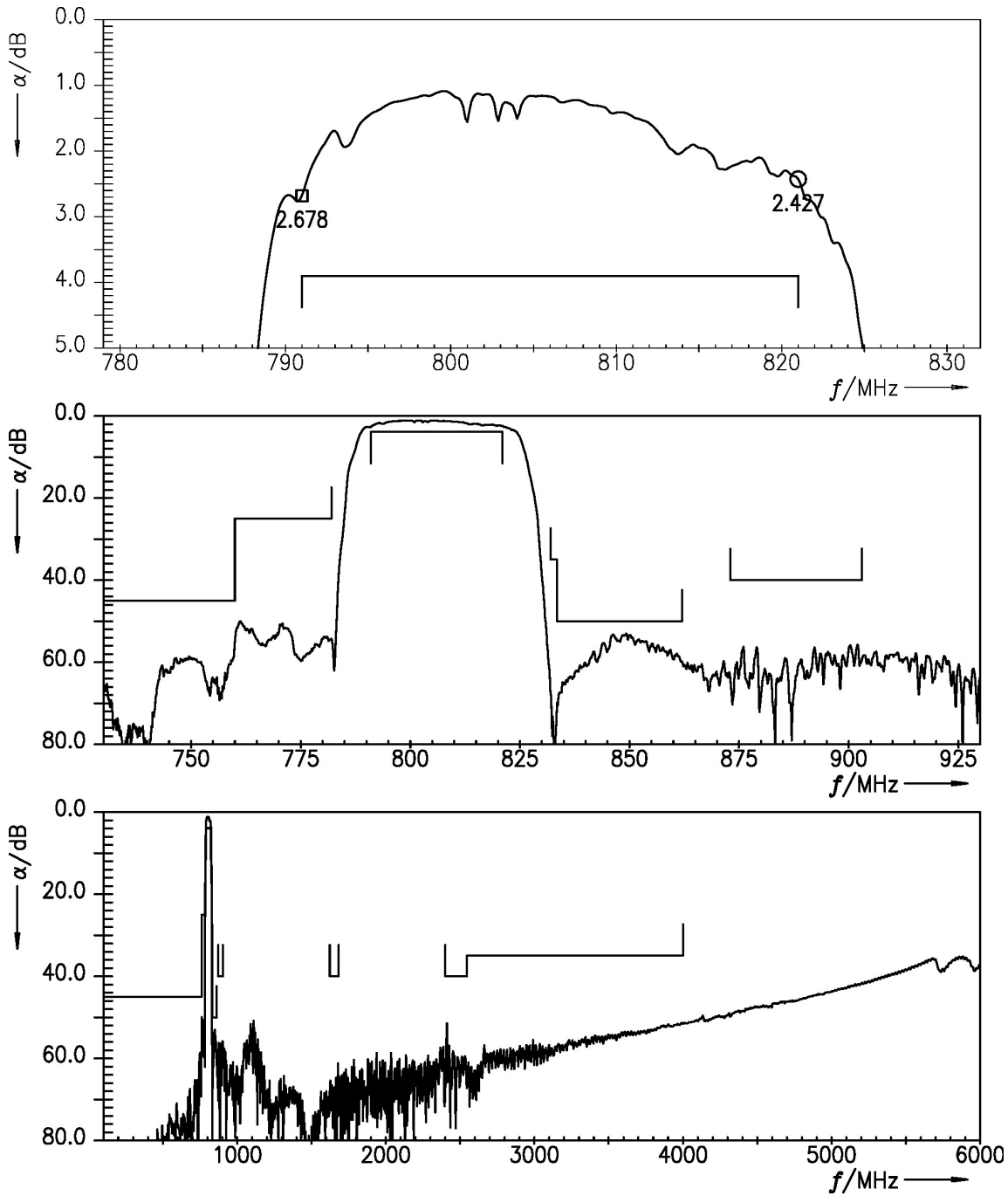


Figure 5: Attenuation ANT – RX.

8.3 TX – RX

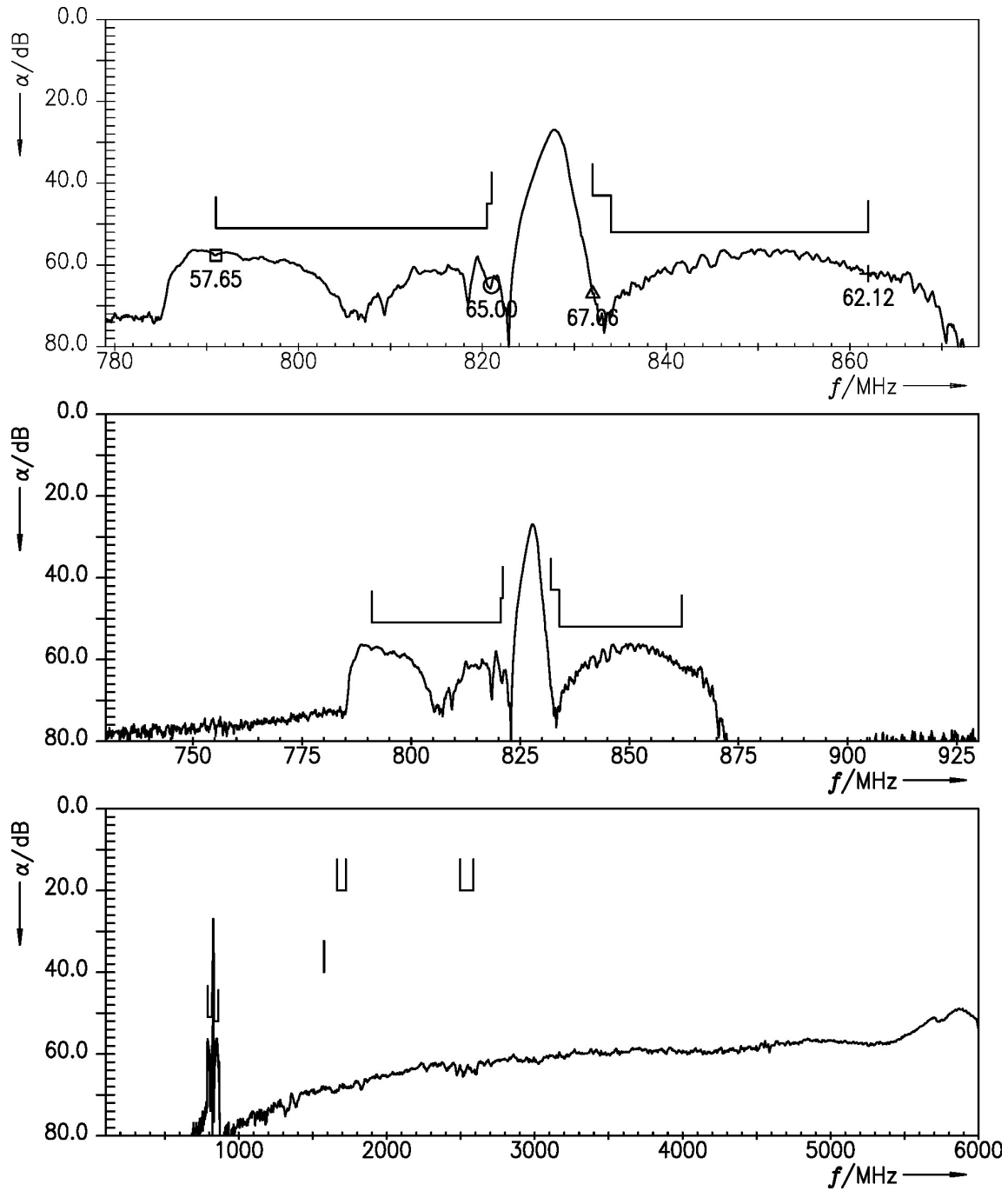


Figure 6: Isolation TX – RX.

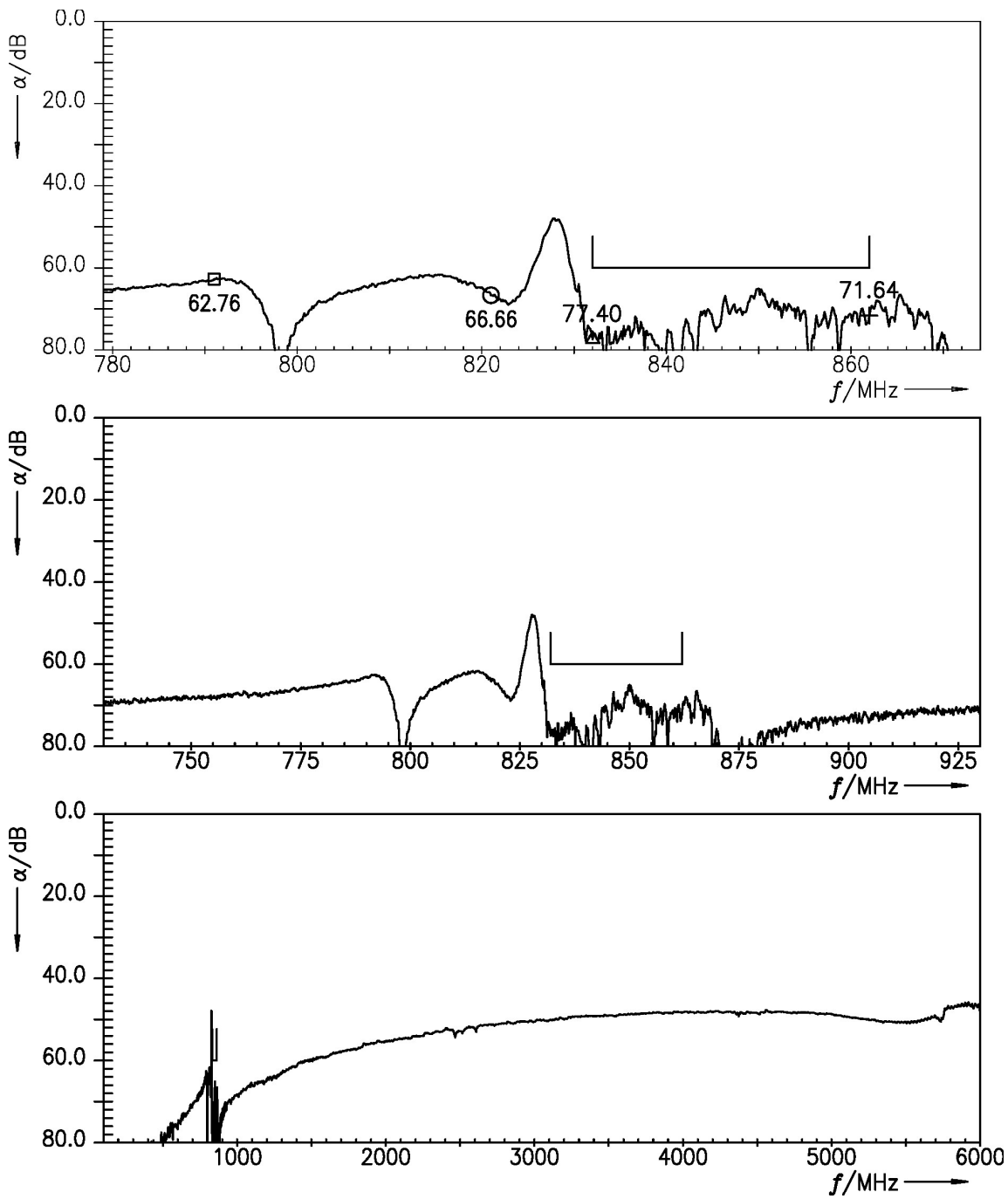


Figure 7: Common-mode isolation TX – RX.

9 Reflection coefficients

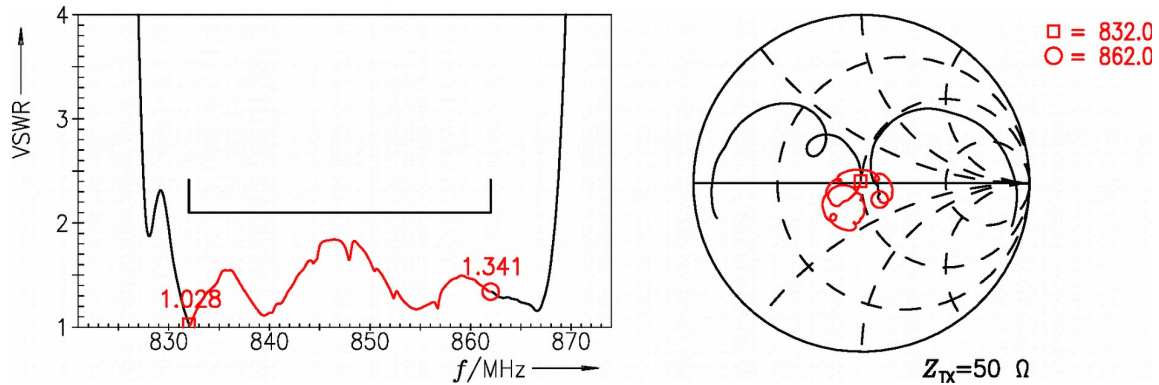


Figure 8: Reflection coefficient at TX port.

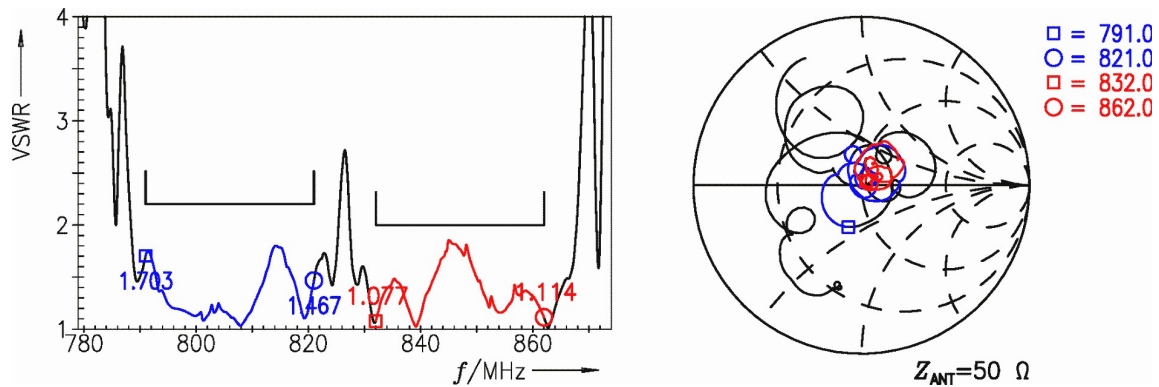


Figure 9: Reflection coefficient at ANT port.

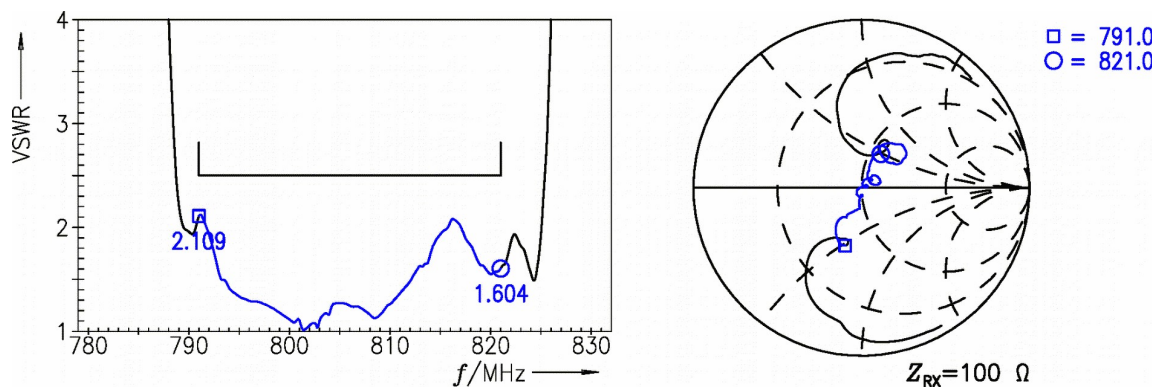


Figure 10: Reflection coefficient at RX port.

10 Packing material

10.1 Tape

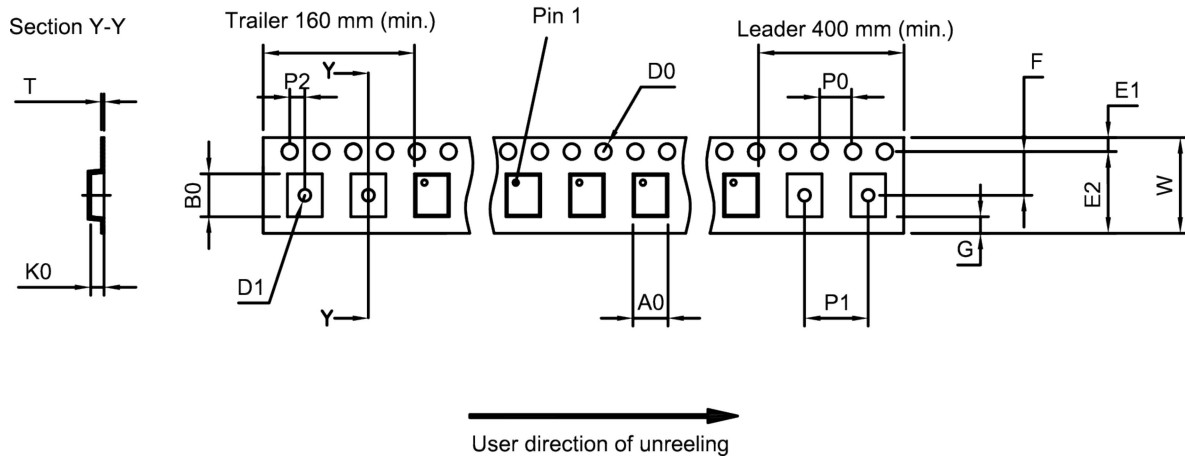


Figure 11: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.8±0.05 mm	E ₂	6.25 mm (min.)	P ₁	4.0±0.1 mm
B ₀	2.25±0.05 mm	F	3.5±0.05 mm	P ₂	2.0±0.05 mm
D ₀	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.03 mm
D ₁	1.0 mm (min.)	K ₀	0.6±0.05 mm	W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

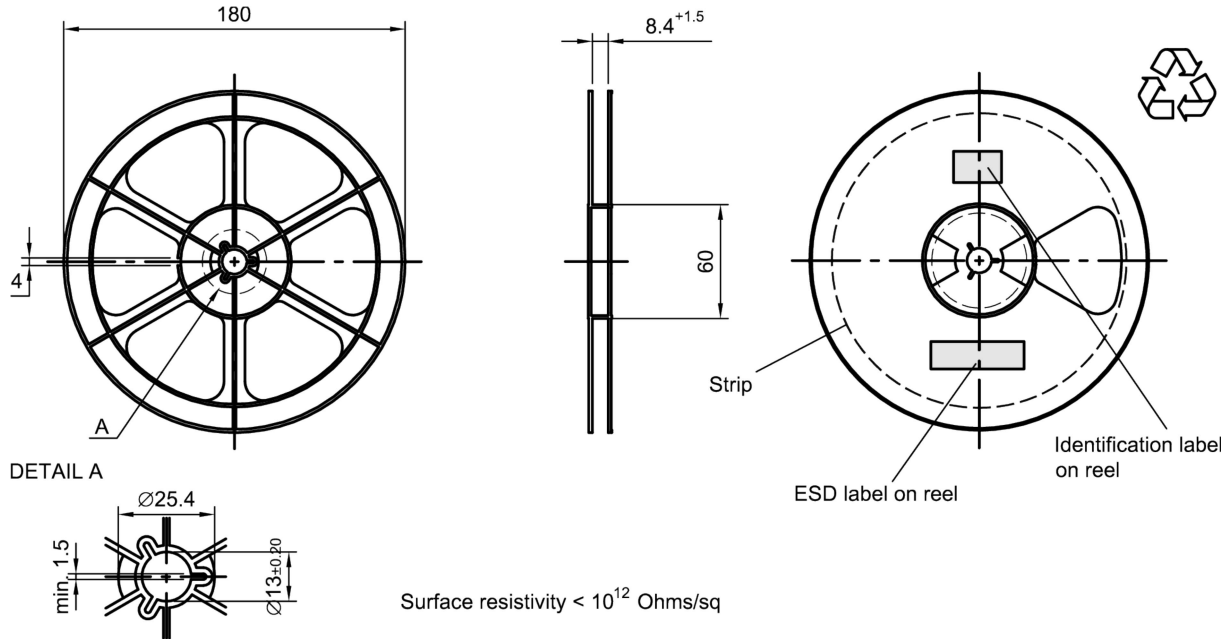


Figure 12: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10 ± 3

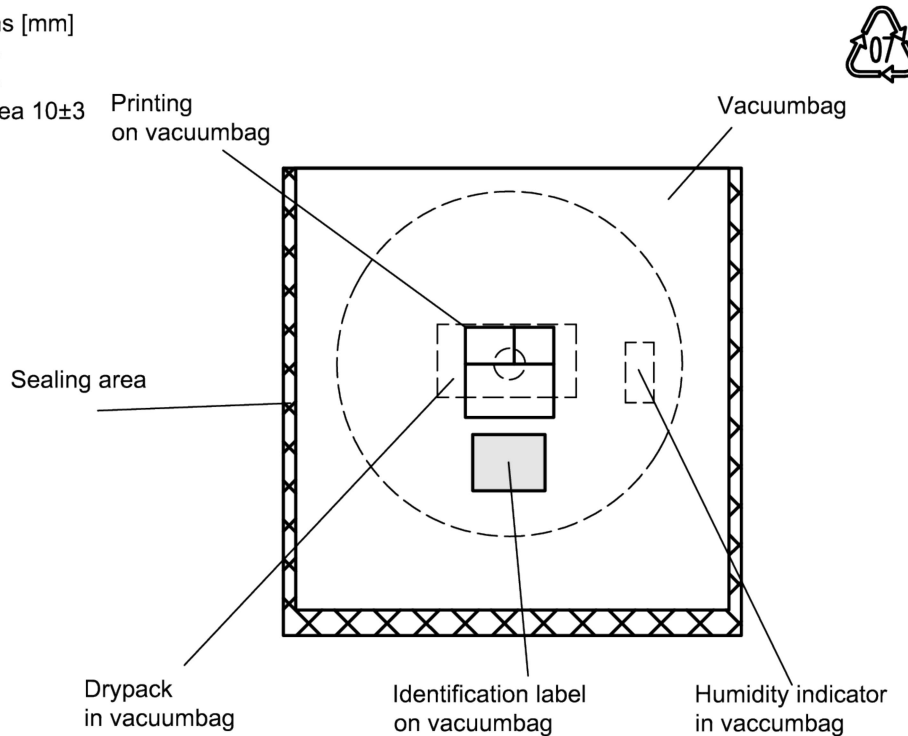


Figure 13: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

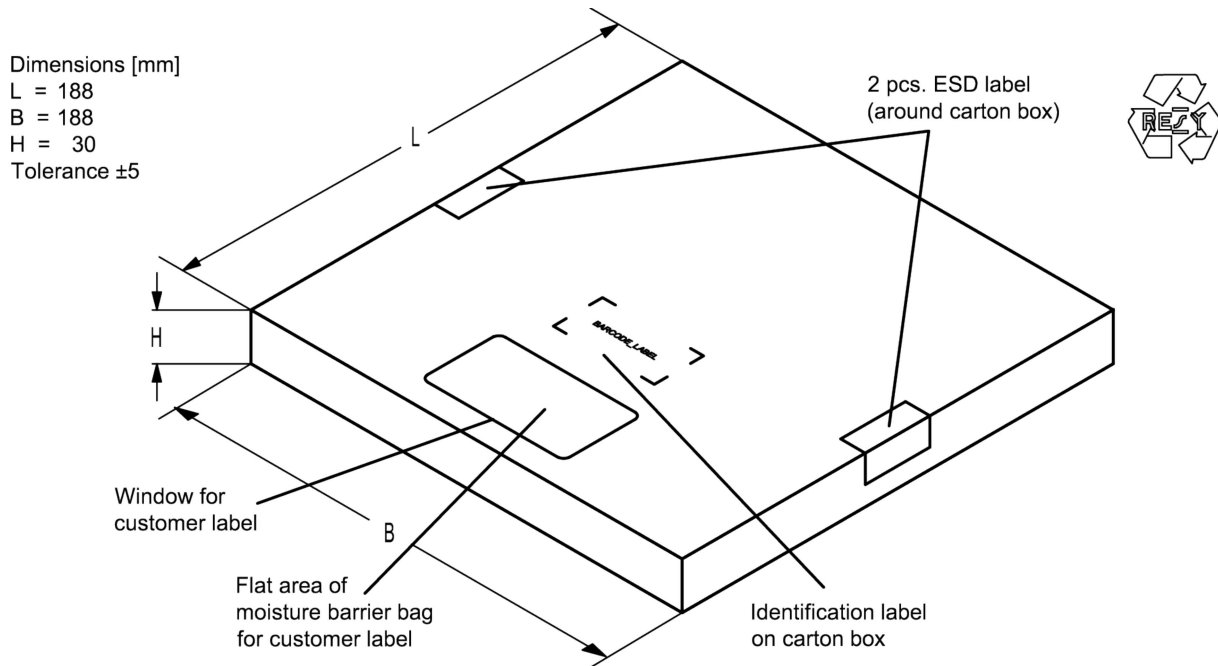


Figure 14: Drawing of folding box for reel with diameter of 180 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.
16J => **1234**
 $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0 =$ **1234**

The BASE32 code for product type B4404 is 49M.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.
5UY => **12345**
 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$ **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220$ °C	30 s to 70 s
$T > 230$ °C	min. 10 s
$T > 245$ °C	max. 20 s
$T \geq 255$ °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

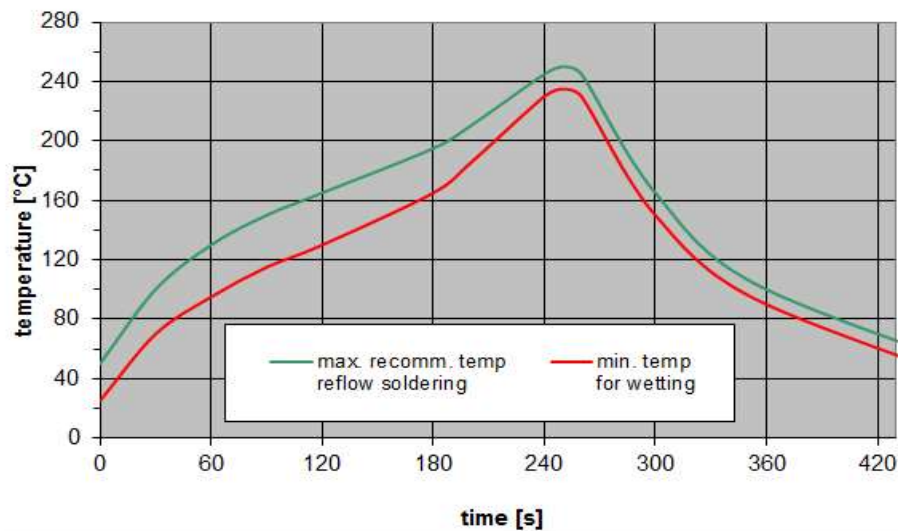


Figure 15: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <https://rfe.qualcomm.com/>.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

15 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
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